

**AMENDMENTS TO THE SPECIFICATION**

**Please replace the paragraph beginning at page 6, line 12 with the following amended paragraph:**

Next, as is shown in Fig. 2C, a protective member 20 is bonded to the main surface A of the substrate 10, so that the electroconductive thin film 12 is held by the protective member 20. Any member that has a flat surface portion and is able to hold the electroconductive thin film 12 by this flat surface portion may be used as the protective member 20 and examples thereof include a glass substrate, semiconductor substrates such as silicon, ceramic substrates, and plastic substrates. It is preferable that the protective member 20 is bonded to the main surface A of the substrate 10 using a hot melt adhesive, an ultraviolet hardening adhesive or the like. A hot melt adhesive is particularly preferable as it allows a protective member 20 that has been attached to the substrate 10 to be removed simply by heating the substrate 10. The protective member may be removed subsequent to the insertion of the electroconductive substance, as described below (see e.g. Fig. 4). Note that it is sufficient if the protective member 20 holds at least the micropore formation portion of the electroconductive thin film 12. However, as is shown in Fig. 2C, it is preferable that the protective member 20 holds the entire electroconductive thin film 12.

**After the third full paragraph on page 4, please insert the following new paragraph:**

Fig. 4 is a cross-sectional view of the main portions showing another embodiment of the method of the present invention.